503629799 12/30/2015

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SHUNPEI YAMAZAKI	06/26/2013

RECEIVING PARTY DATA

Name:	SEMICONDUCTOR ENERGY LABORATORY CO., LTD.	
Street Address:	398, HASE	
City:	ATSUGI-SHI, KANAGAWA-KEN	
State/Country:	JAPAN	
Postal Code:	243-0036	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14935552

CORRESPONDENCE DATA

Fax Number: (877)769-7945

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (202) 783-5070

Email: APSI@fr.com

Correspondent Name: JOHN F. HAYDEN

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Address Line 2: P.O.BOX 1022

Address Line 4: MINNEAPOLIS, MINNESOTA 55440-1022

ATTORNEY DOCKET NUMBER:	12732-1219002	
NAME OF SUBMITTER:	JANELLE A. JACKSON	
SIGNATURE:	/Janelle A. Jackson/	
DATE SIGNED:	12/30/2015	

Total Attachments: 1

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PATENT 503629799 REEL: 037382 FRAME: 0957

Attorney Docket No. 12732-1219002 Client Ref. US17312-C1

ASSIGNMENT

For valuable consideration, I, <u>Shunpei YAMAZAKI of Setagaya</u>, <u>Tokyo</u>, <u>Japan</u> hereby assign to <u>Semiconductor Energy Laboratory Co., Ltd.</u>, a <u>Japanese</u> corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by me this day, entitled **SEMICONDUCTOR DEVICE AND METHOD FOR** MANUFACTURING THE SAME, filed July 3, 2013 , and assigned U.S. Serial Number 13/934, 274 , and I authorize and request the Assignee or the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements. and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and I agree for myself and my respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature

Name:

RECORDED: 12/30/2015

Date:

Shunpei YAMAZAKI

PATENT REEL: 037382 FRAME: 0958